

FIG. 1A FORMATION OF BASE FILM / AMORPHOUS SEMICONDUCTOR FILM

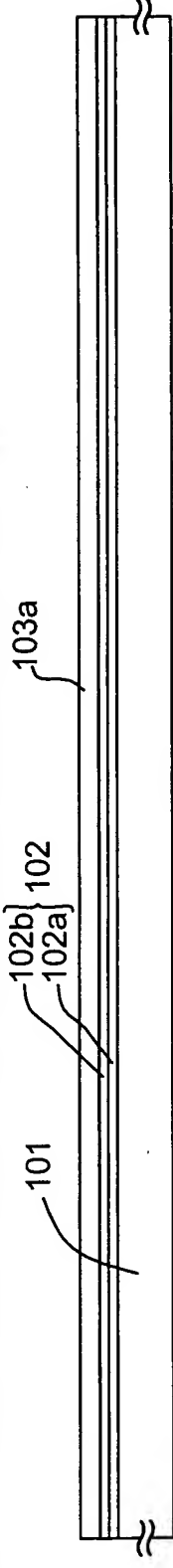


FIG. 1B CRYSTALLIZATION STEP

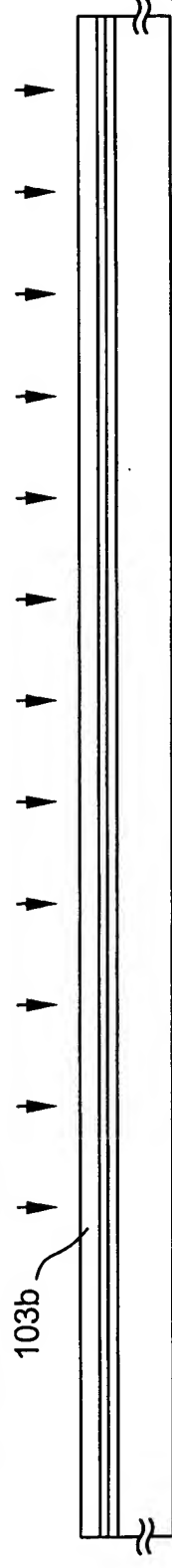


FIG. 1C FORMATION OF ISLAND - LIKE SEMICONDUCTOR LAYER / GATE INSULATING FILM

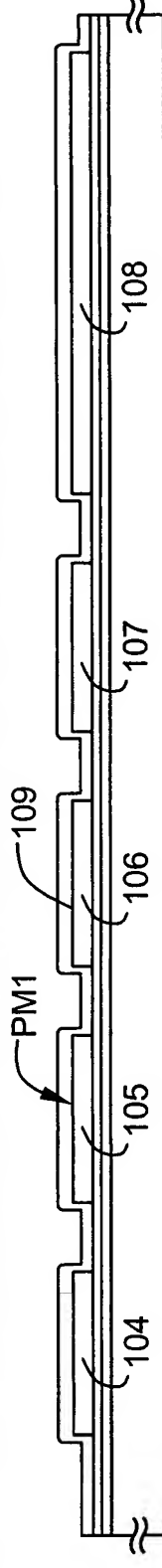


FIG. 1D FORMATION OF HEAT - RESISTANT CONDUCTIVE LAYER

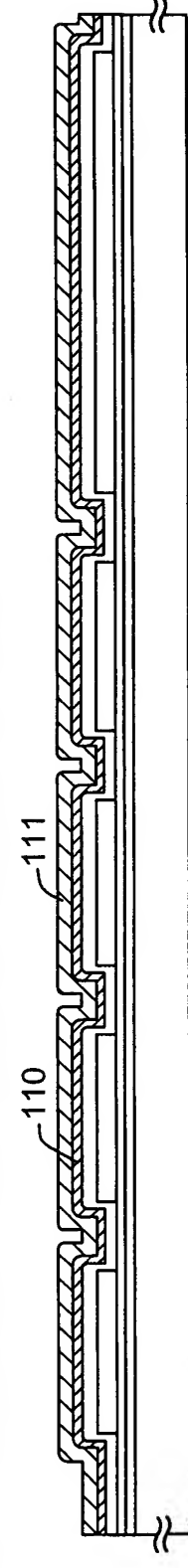
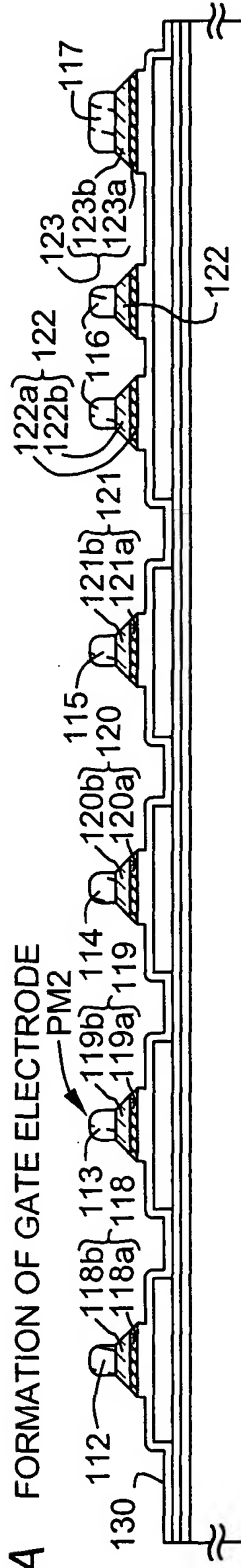
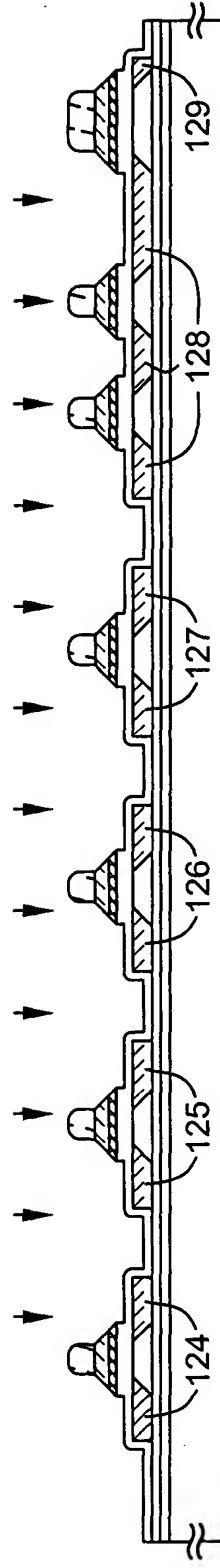


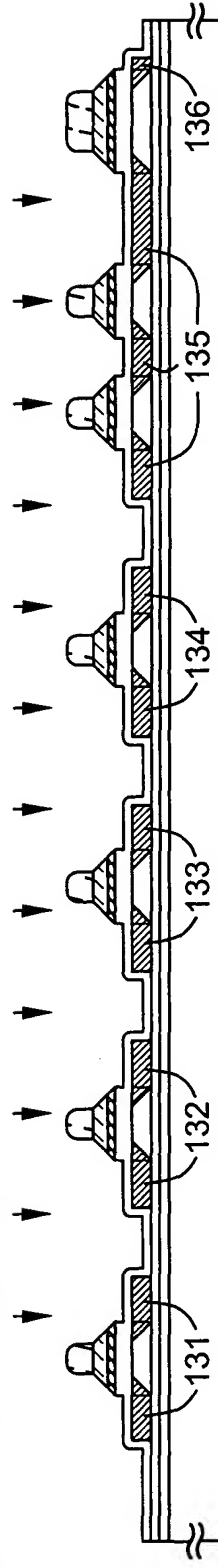
FIG. 2A FORMATION OF GATE ELECTRODE



**FIG. 2B**  $n^-$  DOPE PROCESS



**FIG. 2C**  $n^+$  DOPE PROCESS



**FIG. 2D**  $p^+$  DOPE PROCESS

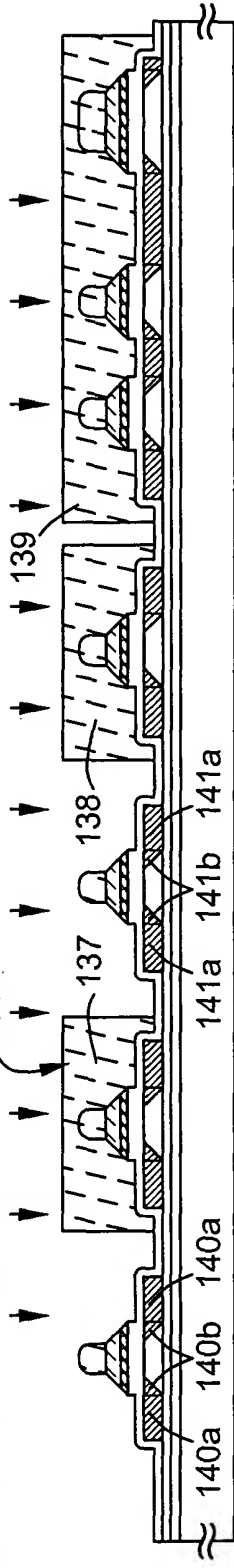


FIG. 3A FORMATION OF FIRST INTERLAYER INSULATING FILM

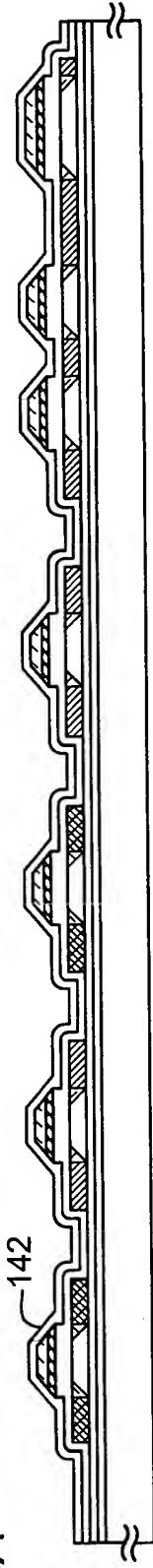


FIG. 3B ACTIVATING STEP

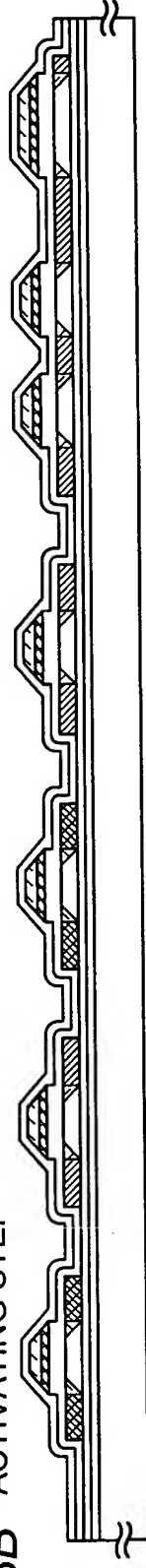
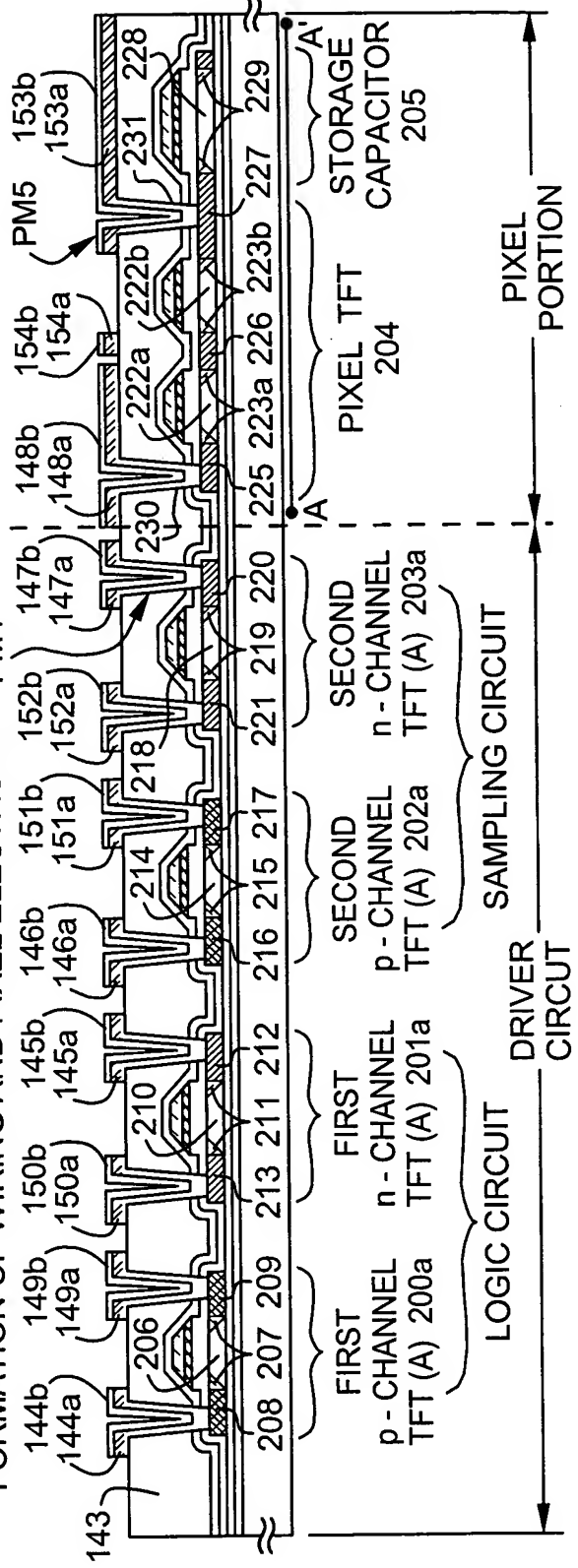
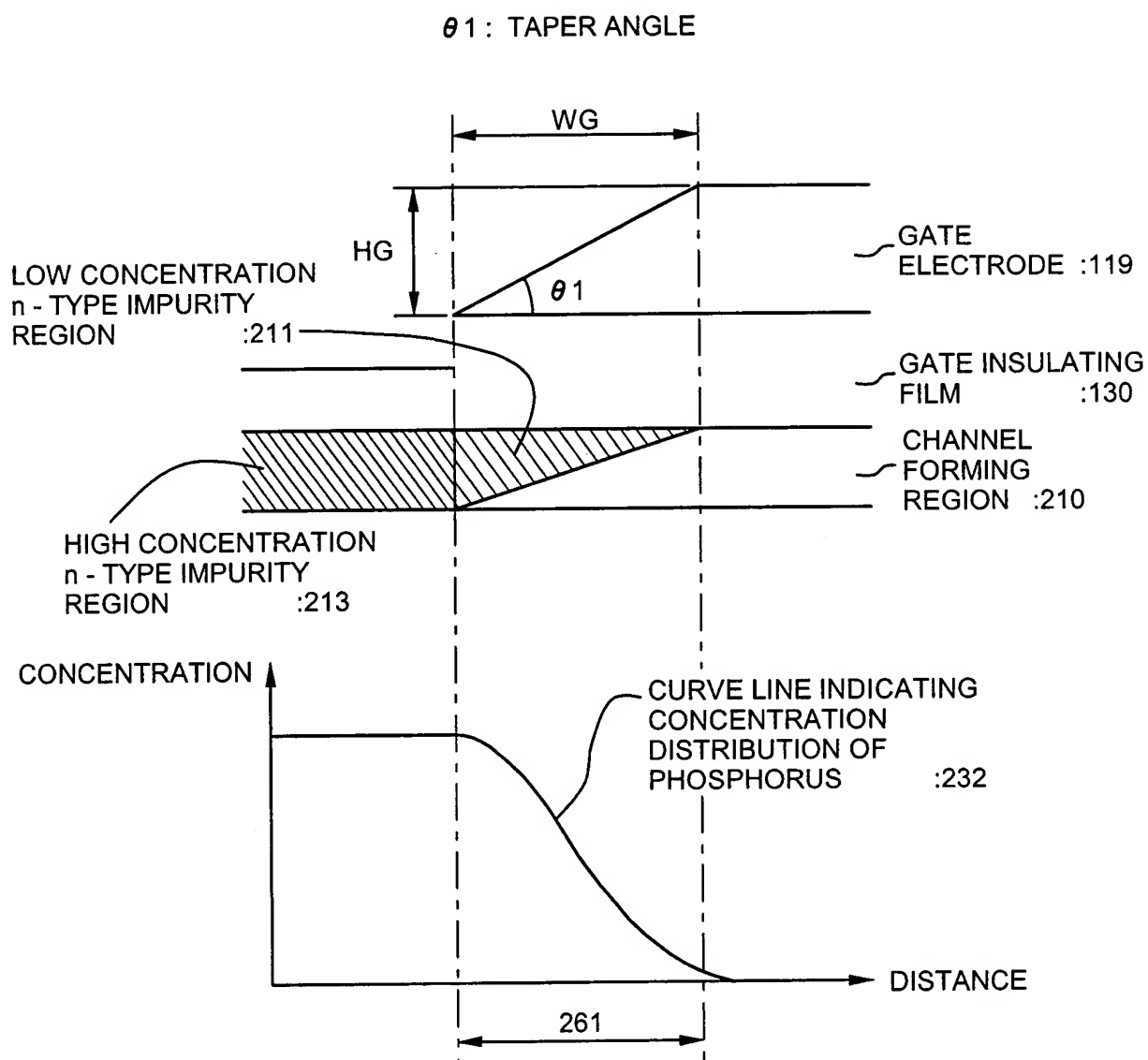


FIG. 3C FORMATION OF SECOND INTERLAYER INSULATION FILM / PERFORATION OF CONTACT HOLE / FORMATION OF WIRING AND PIXEL ELECTRODE PM4





**FIG. 4**

FIG. 5A ACTIVATING STEP

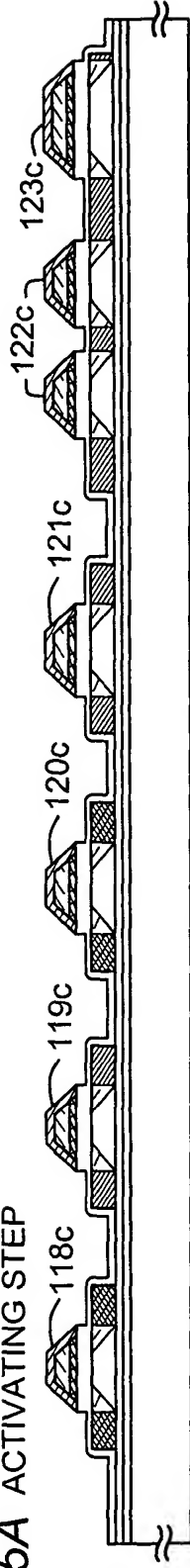


FIG. 5B FORMATION OF LOW-RESISTANT WIRING / FORMATION OF FIRST INTERLAYER INSULATING FILM

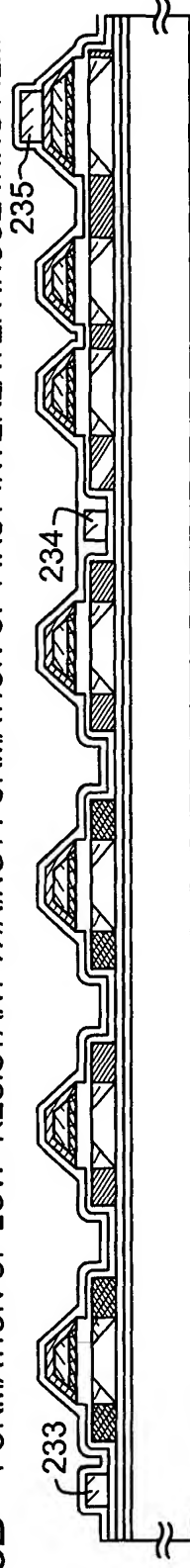
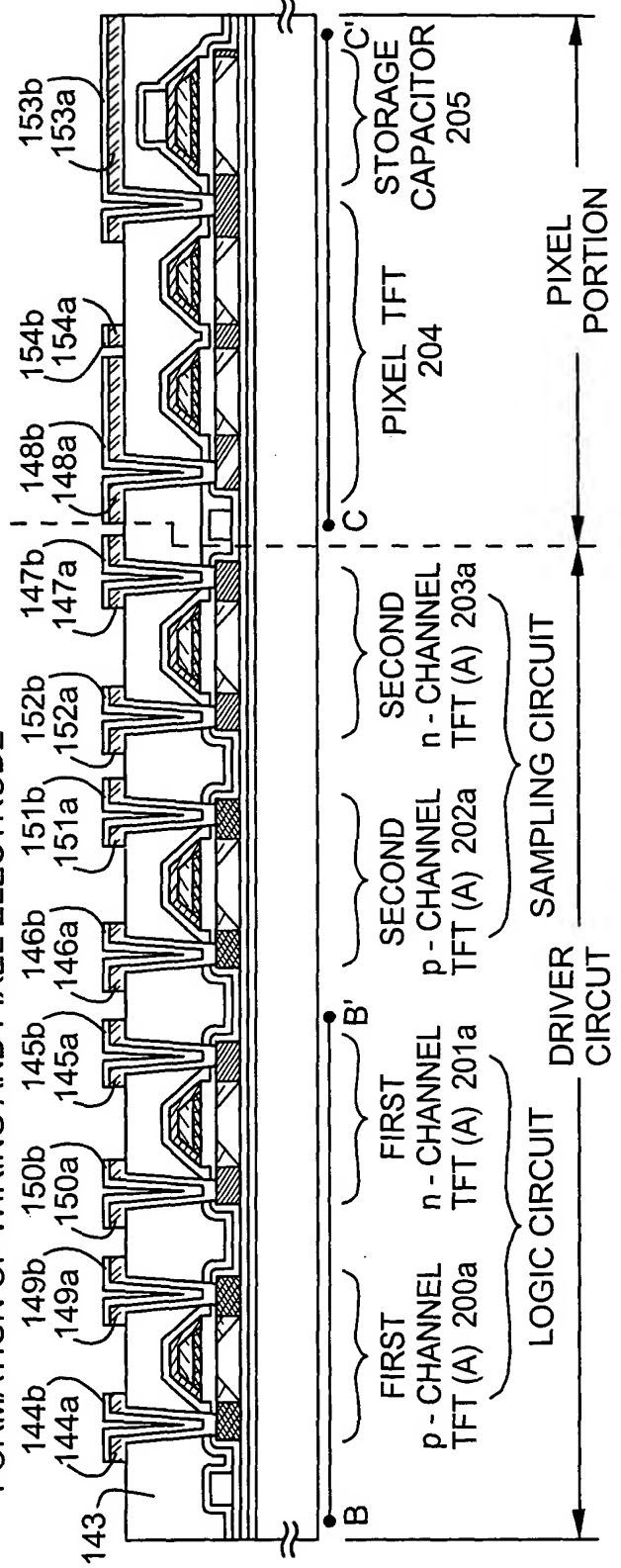


FIG. 5C FORMATION OF SECOND INTERLAYER INSULATION FILM / PERFORATION OF CONTACT HOLE / FORMATION OF WIRING AND PIXEL ELECTRODE



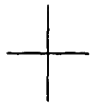


FIG. 6A

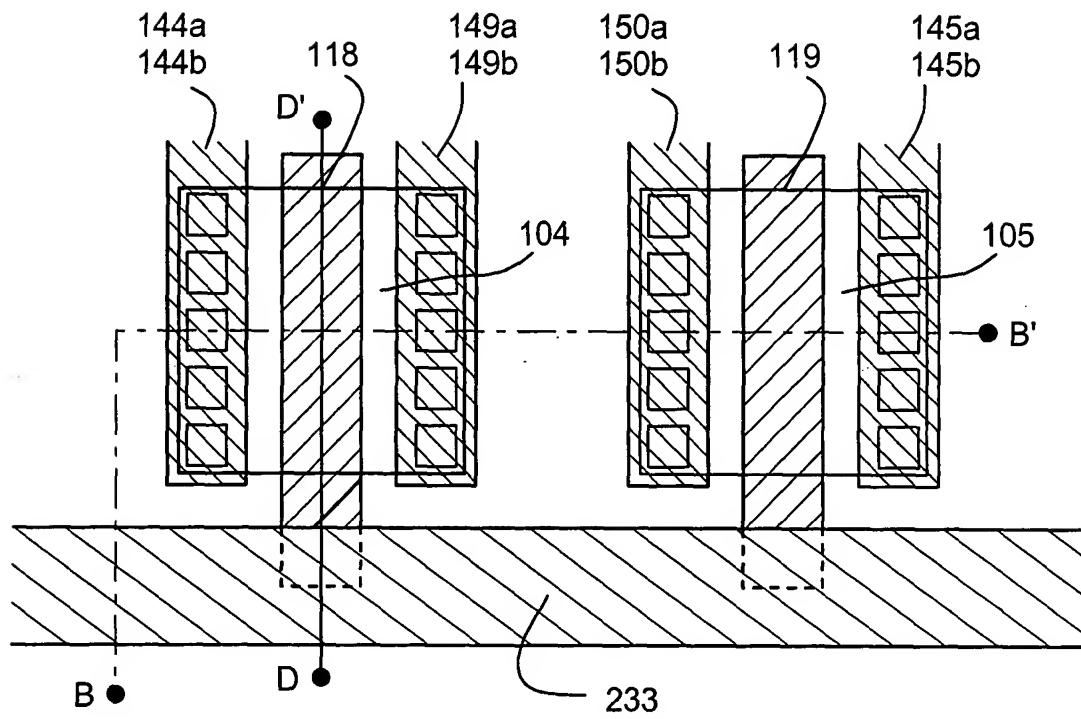


FIG. 6B

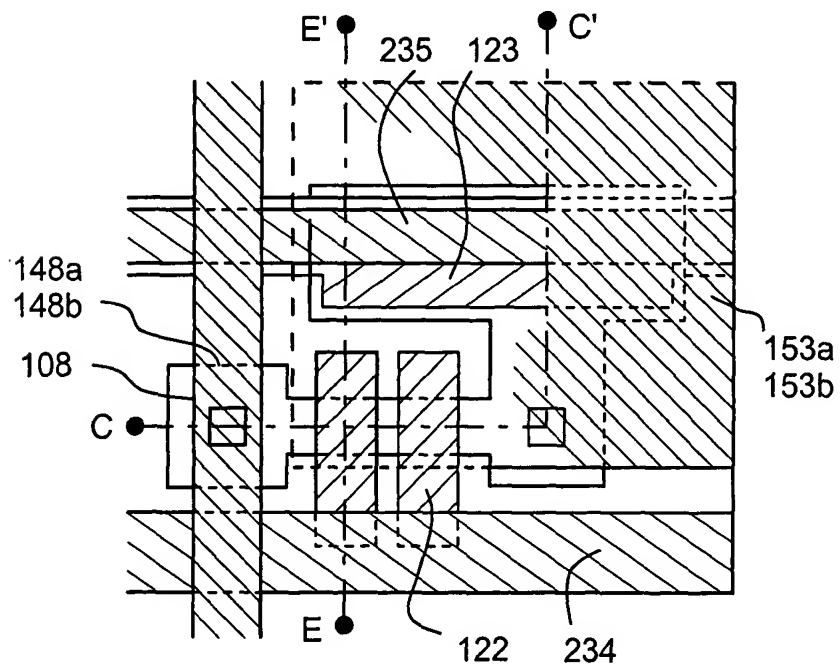


FIG. 7A

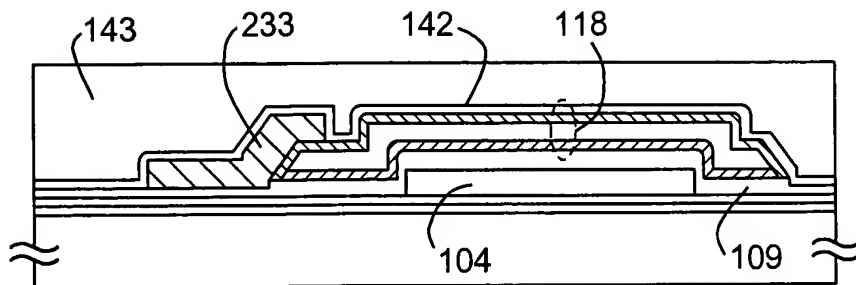


FIG. 7B

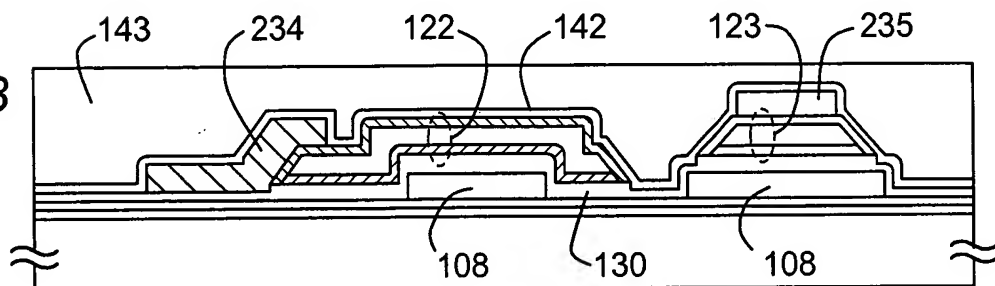


FIG. 8A

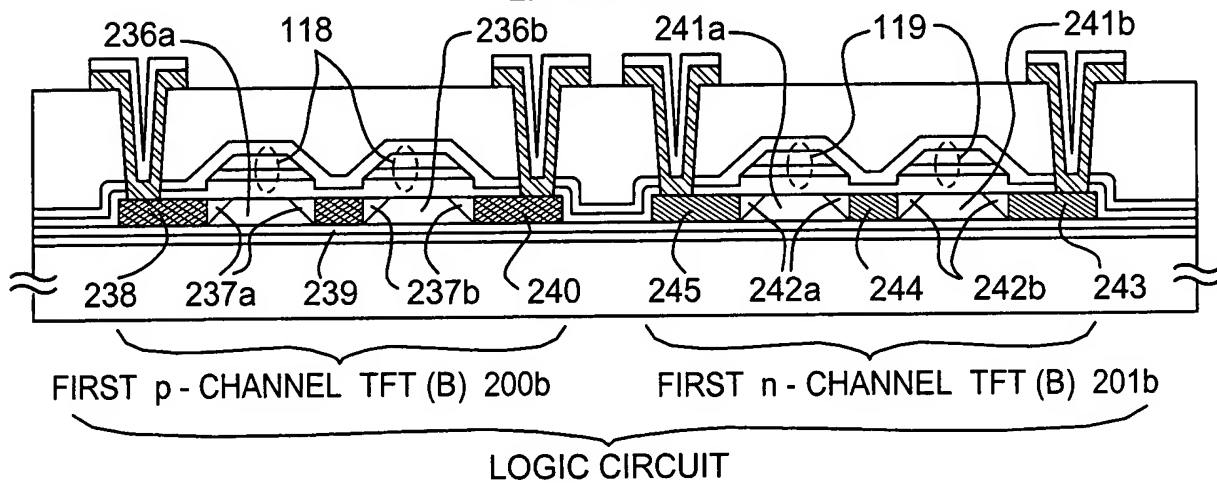


FIG. 8B

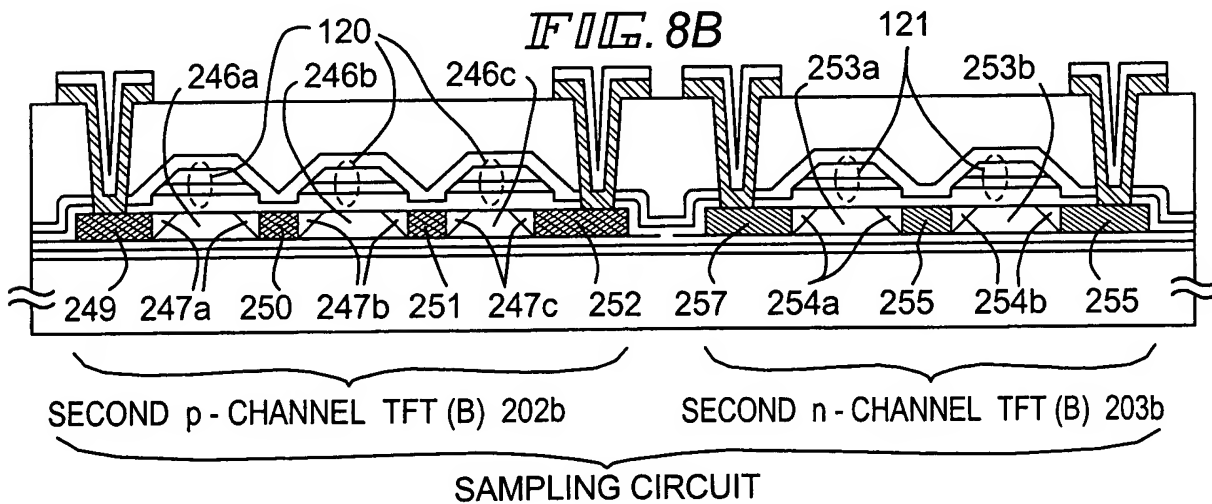


FIG. 9A

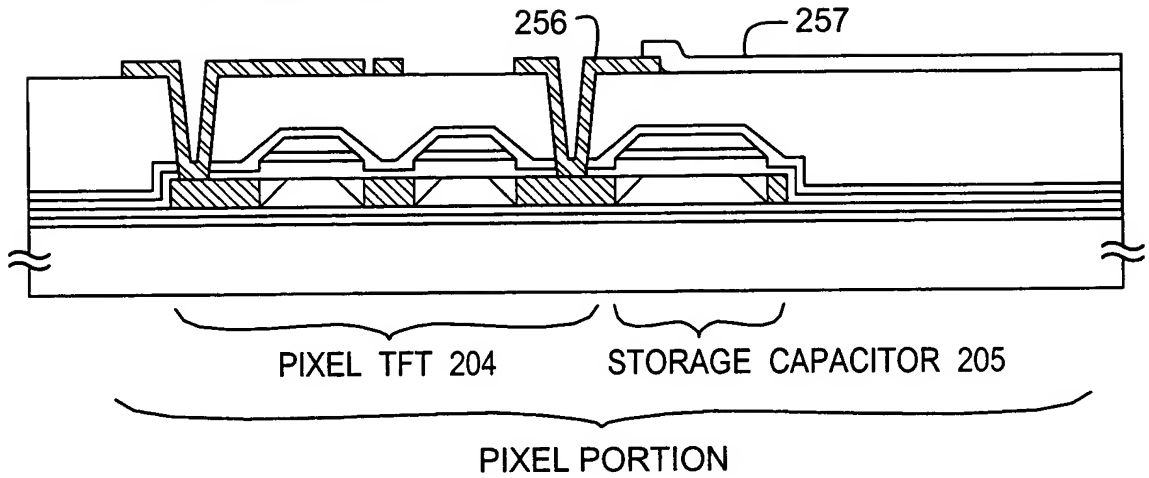


FIG. 9B

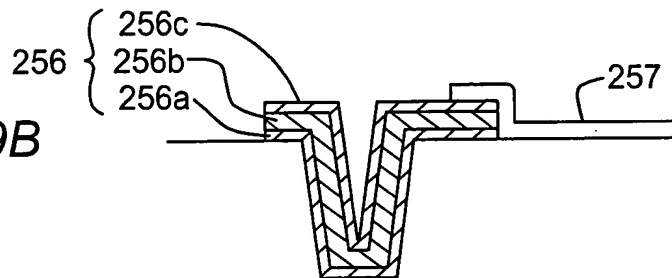


FIG. 9C

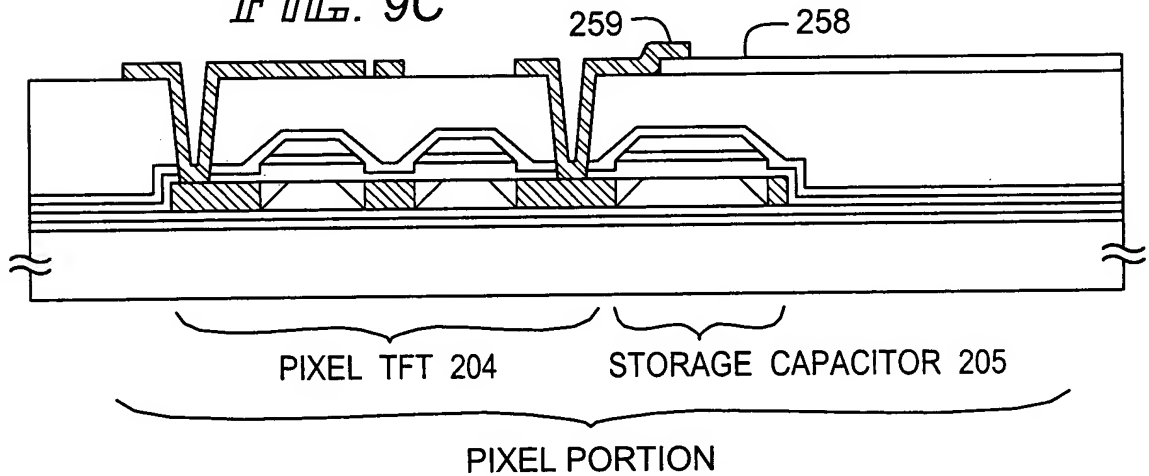
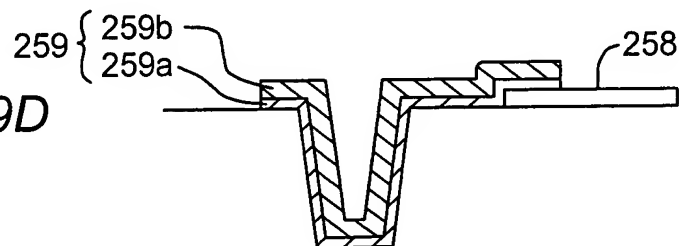


FIG. 9D





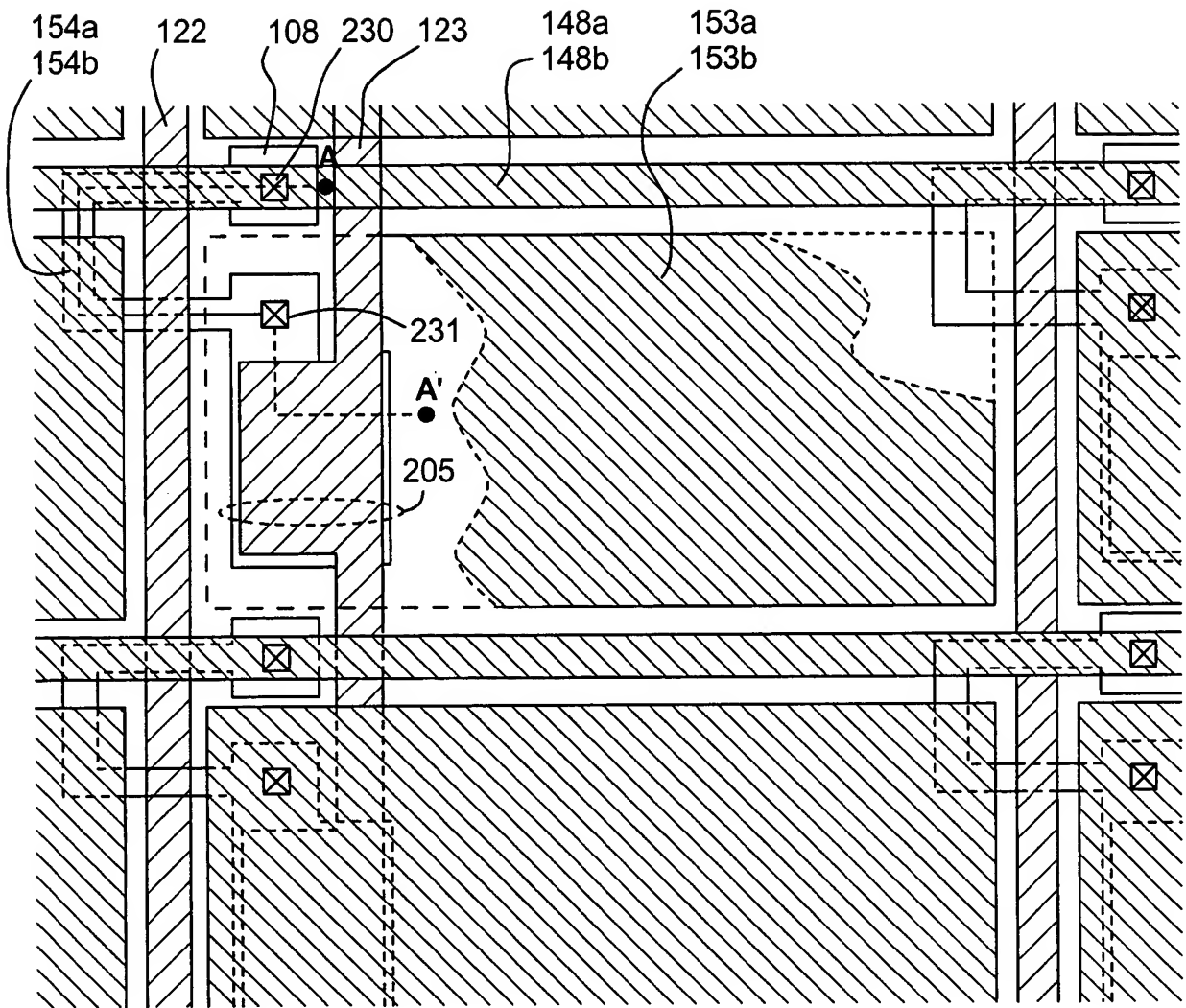


FIG. 10

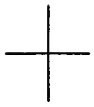


FIG. 11A

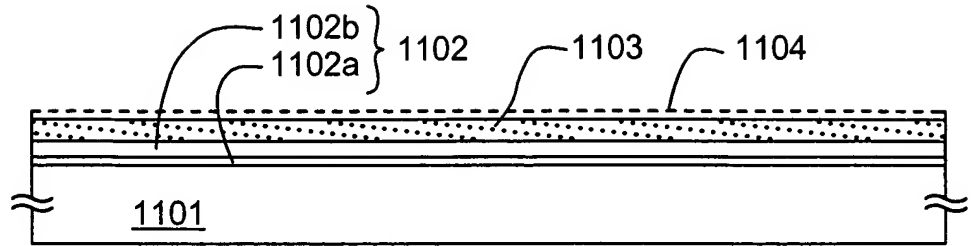


FIG. 11B

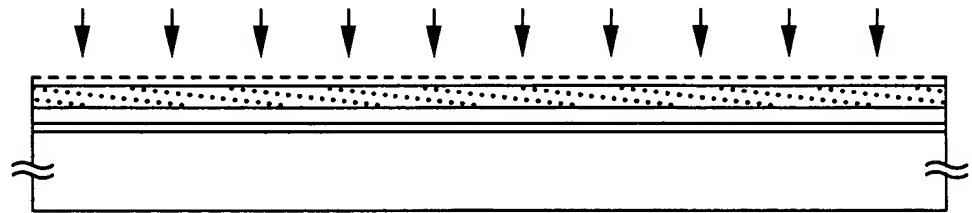


FIG. 11C

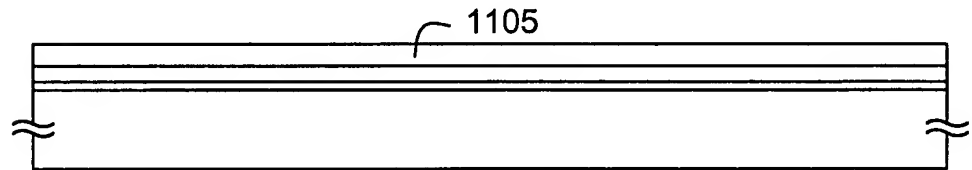


FIG. 12A

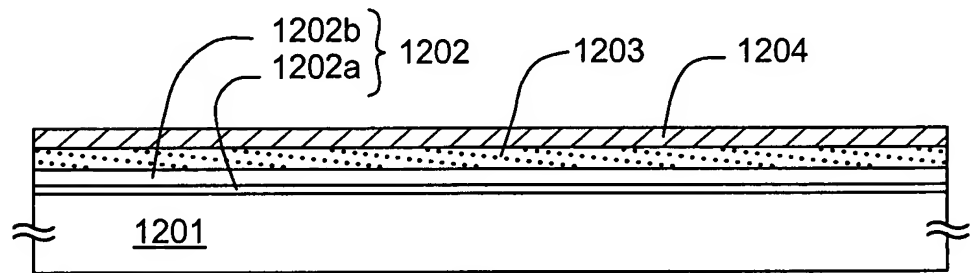


FIG. 12B

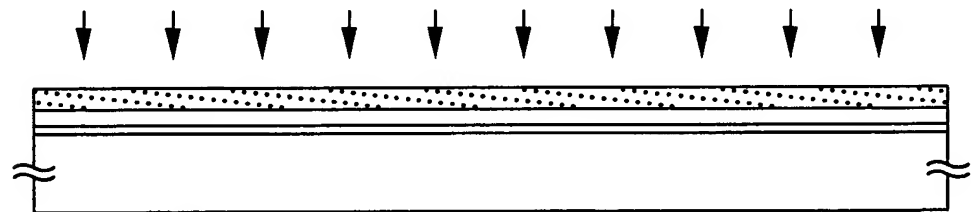


FIG. 12C

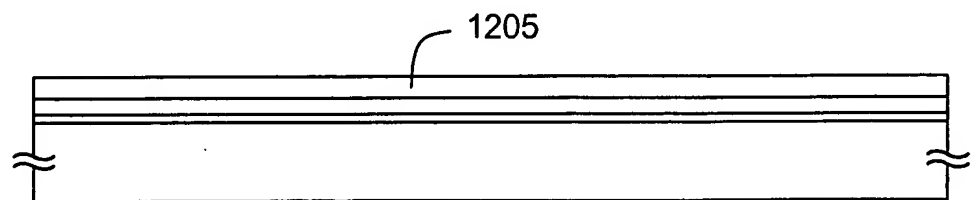


FIG. 13 ACTIVATING STEP

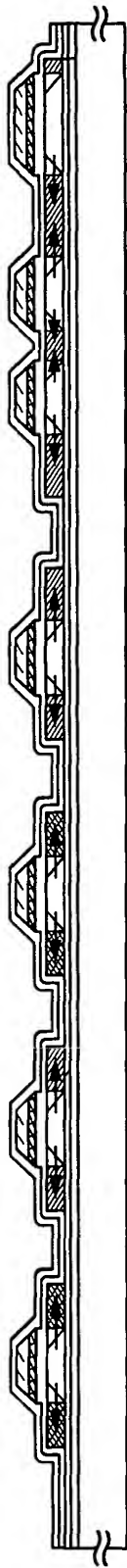


FIG. 14A

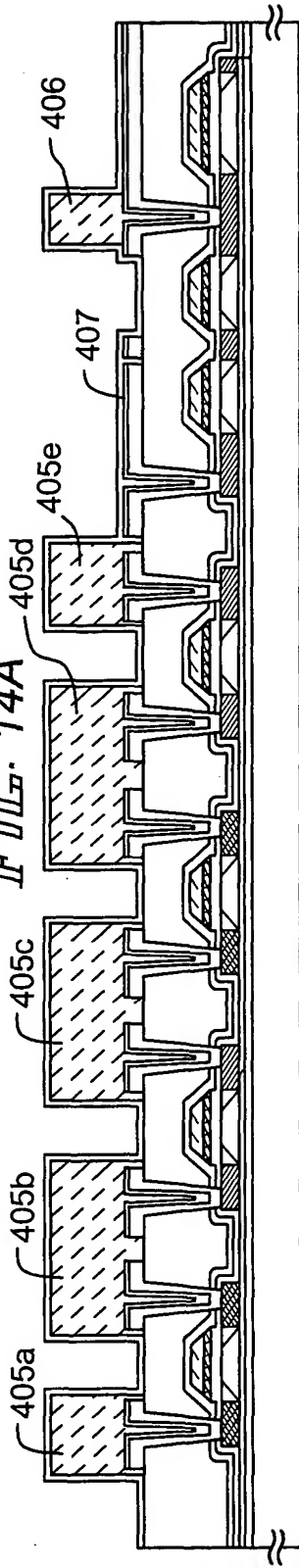


FIG. 14B

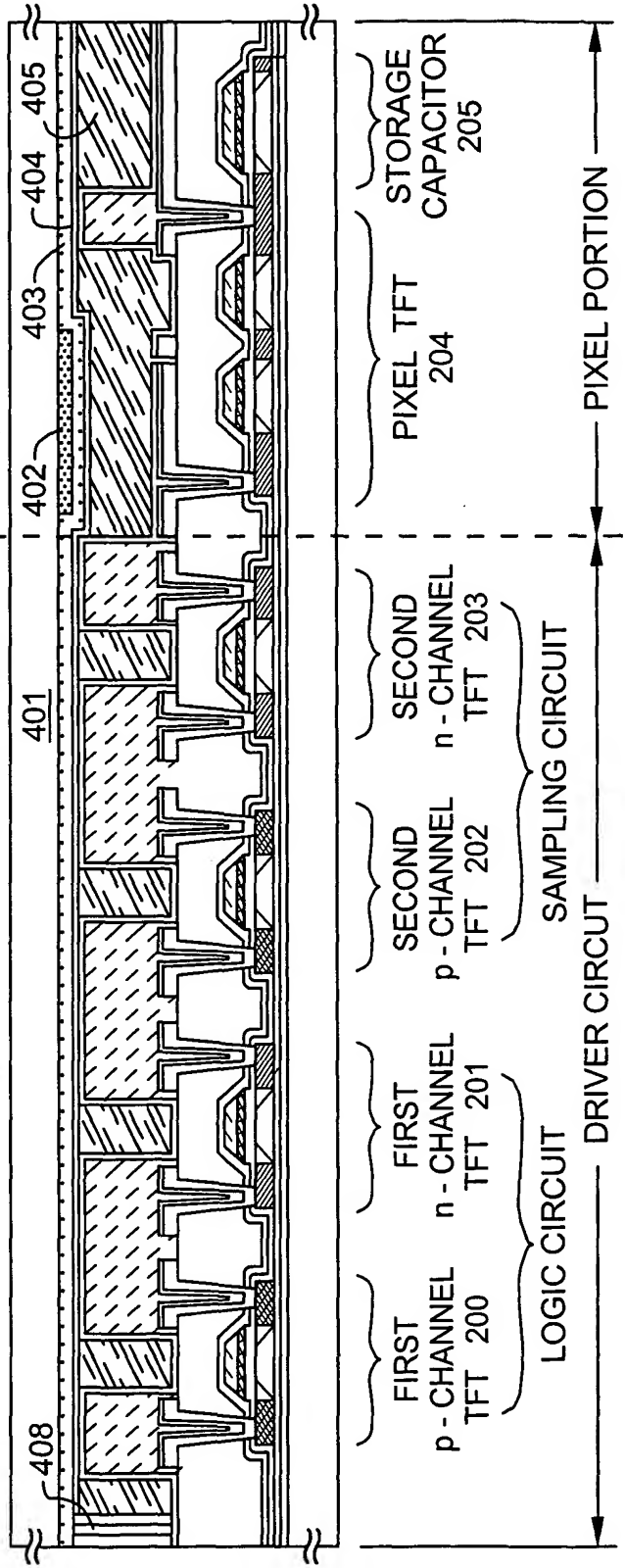


FIG. 15

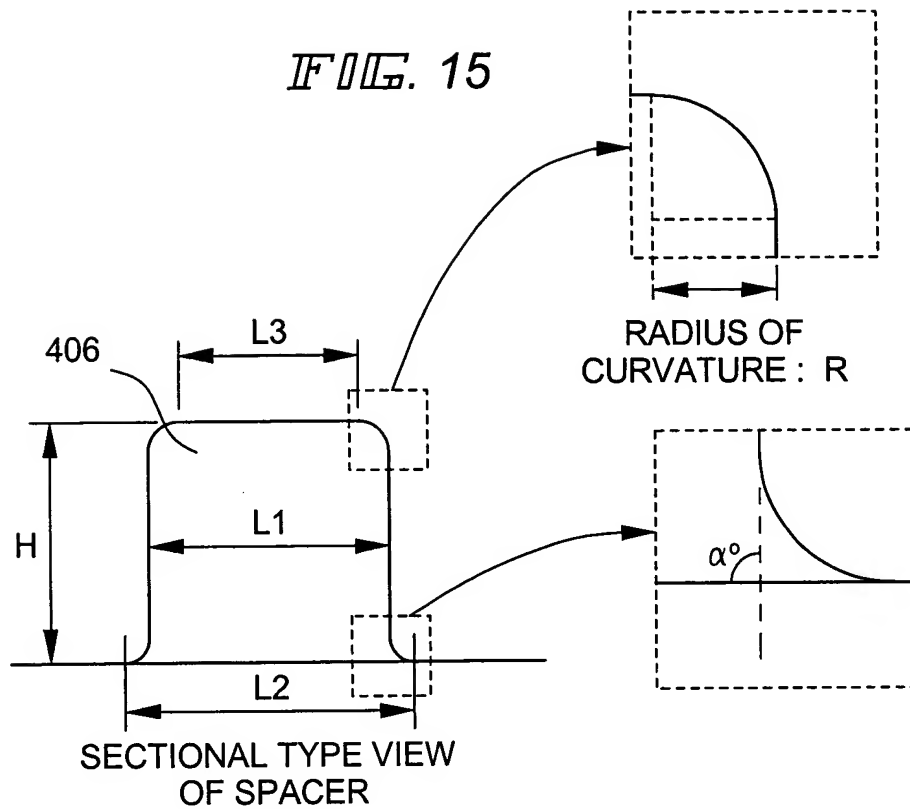


FIG. 16

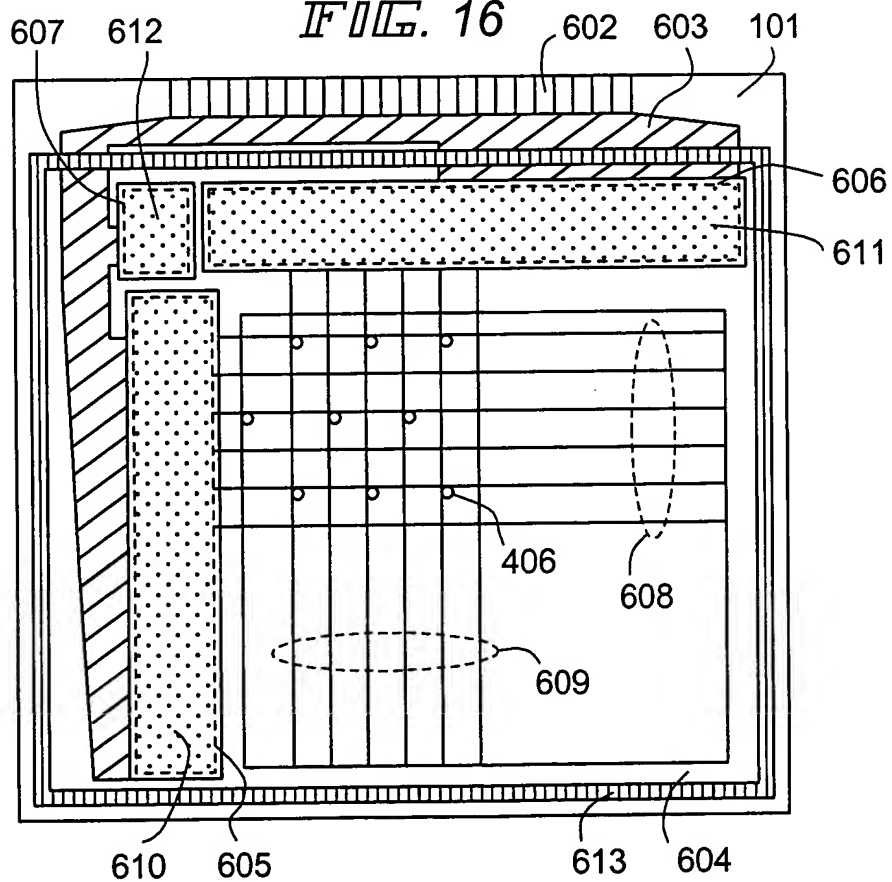


FIG. 17

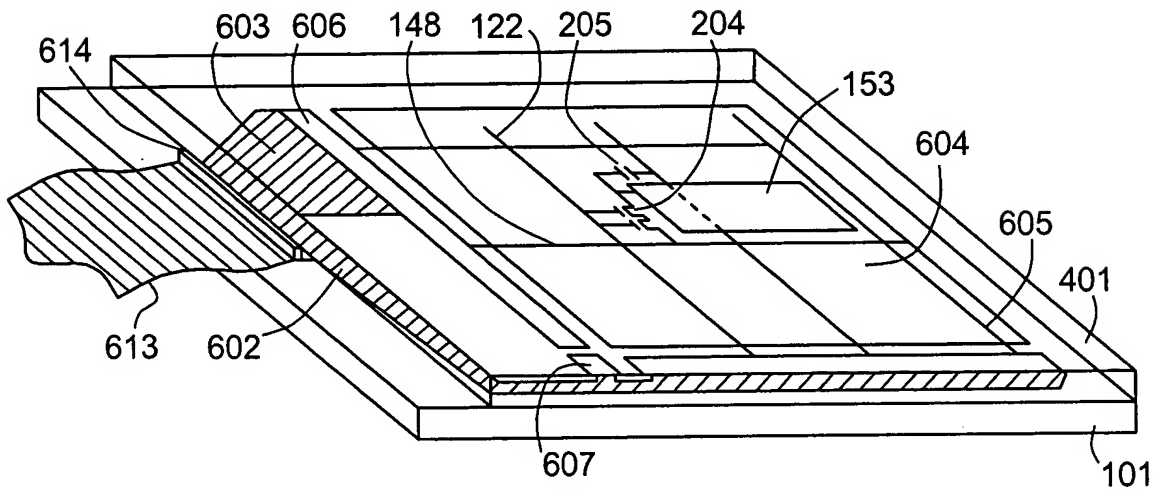


FIG. 18

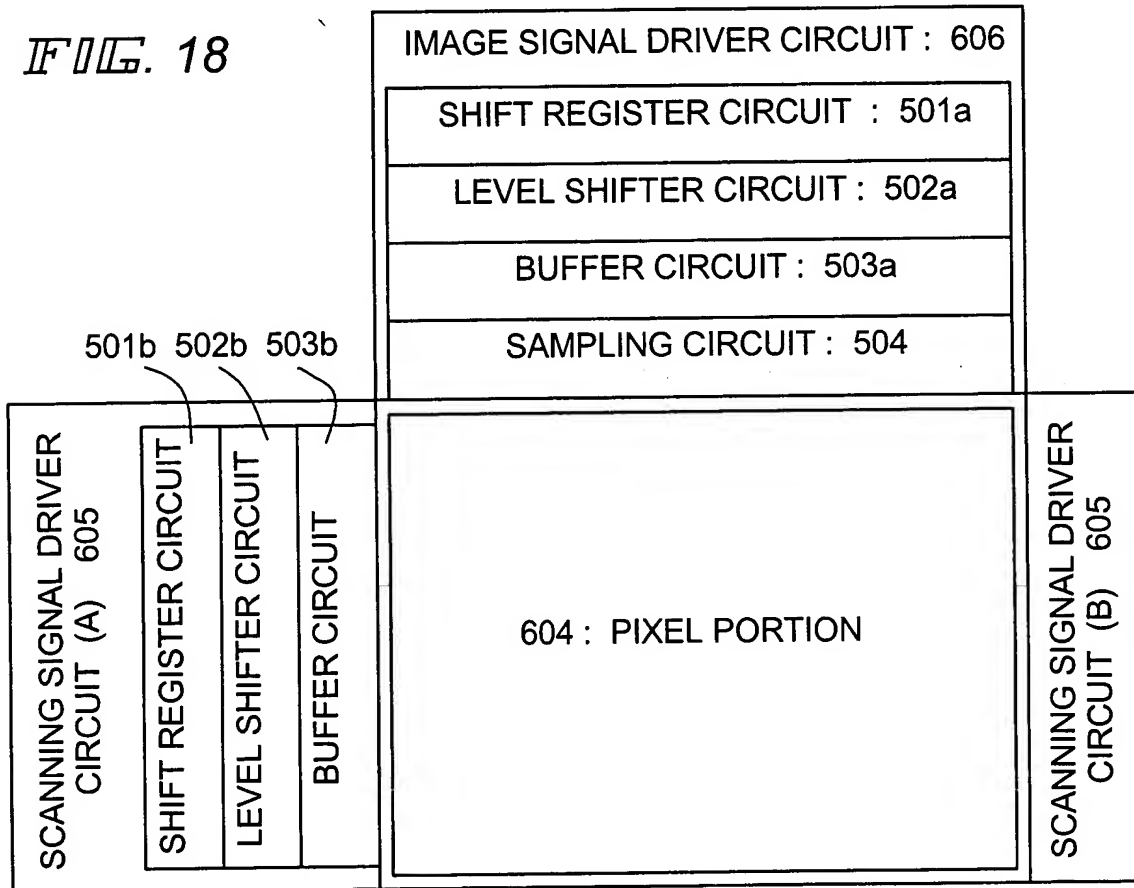


FIG. 19A

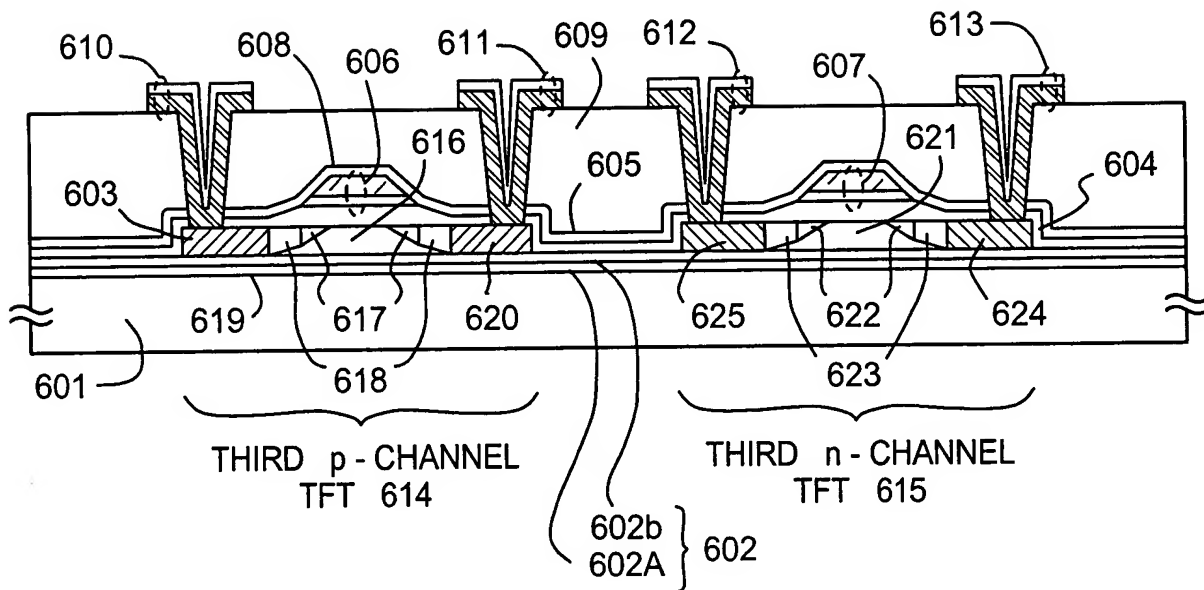


FIG. 19B

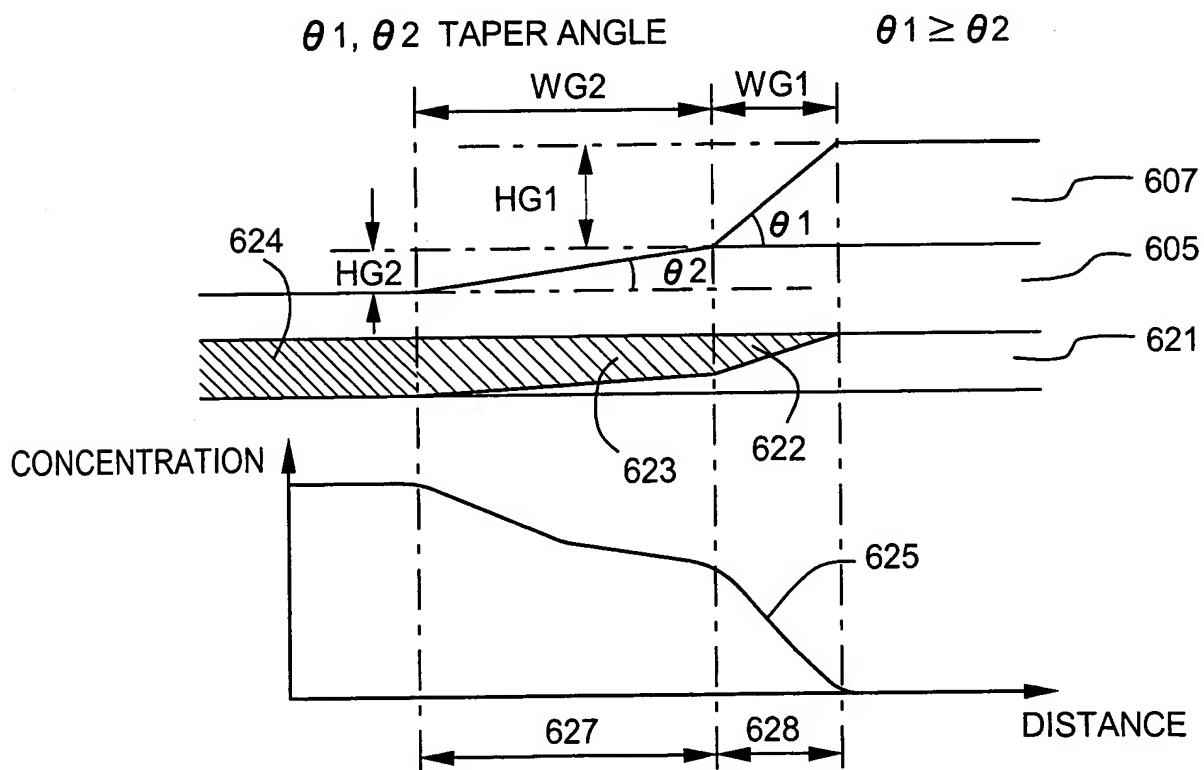


FIG. 20A

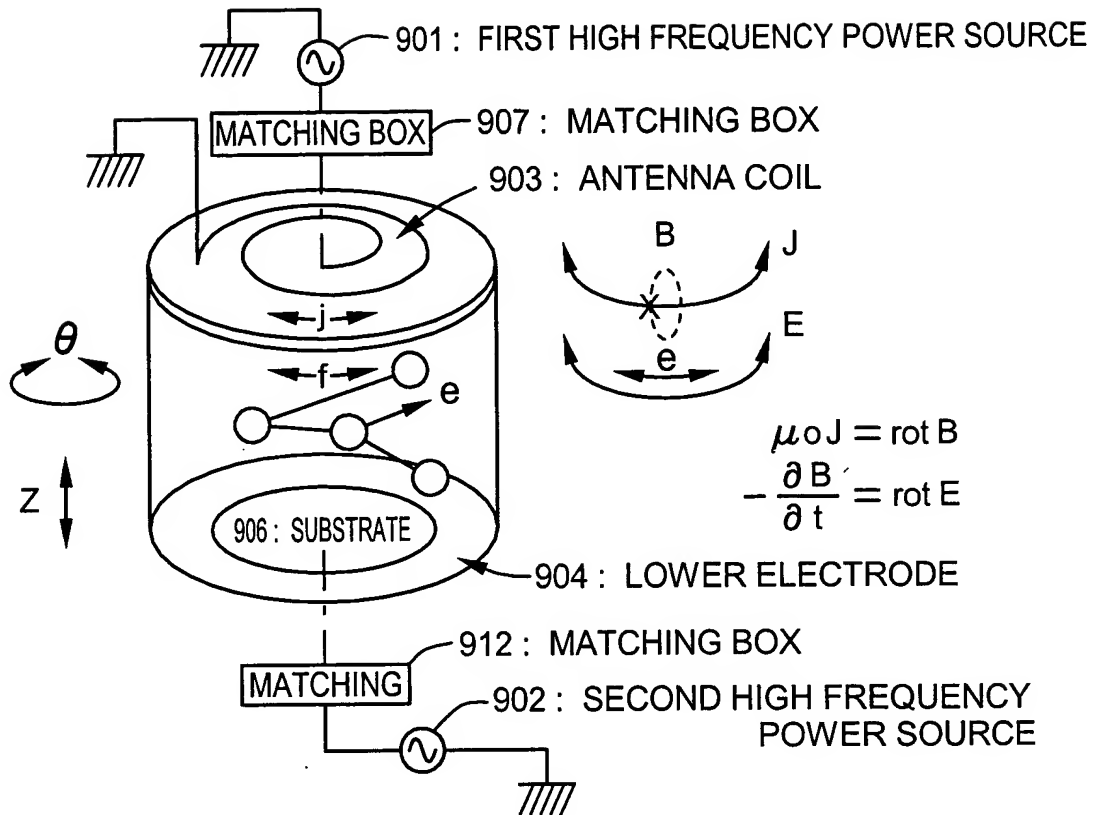
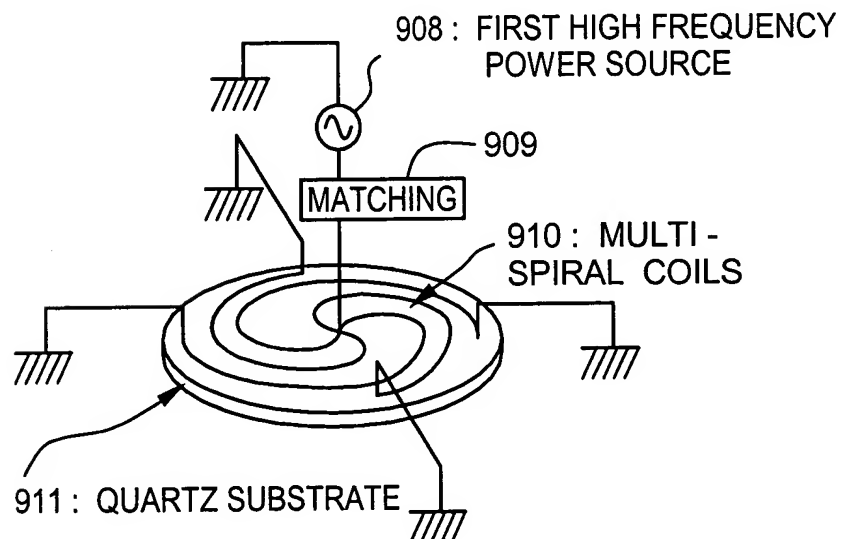
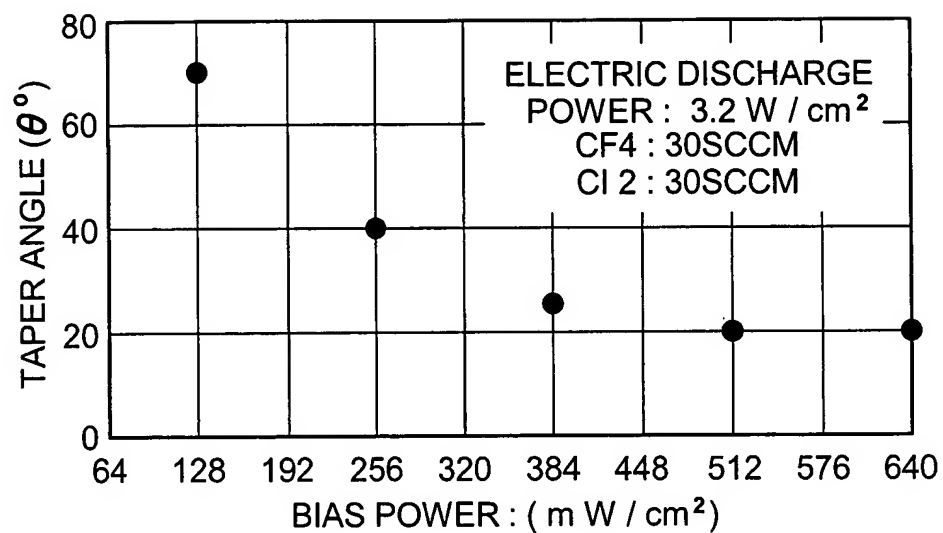


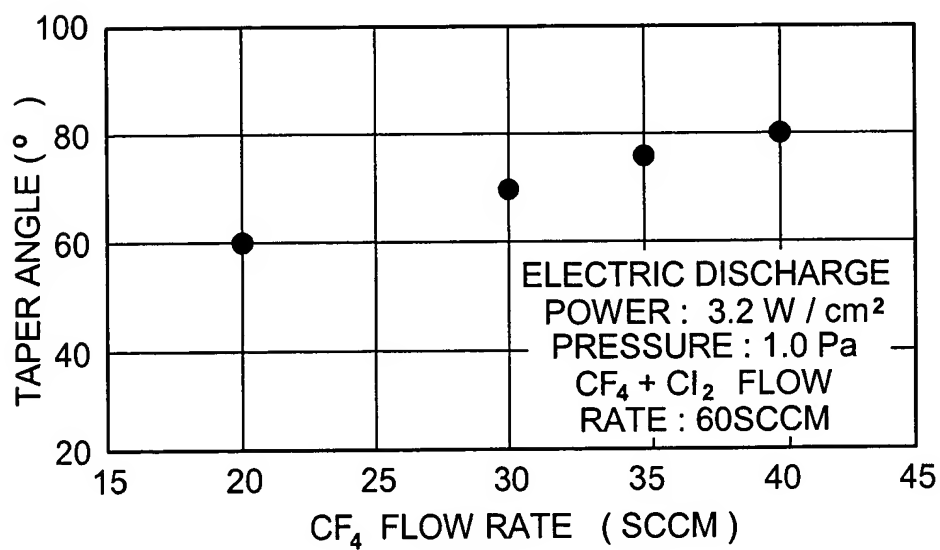
FIG. 20B





DEPENDENCE OF TAPER ANGLE ON BIAS POWER

FIG. 21A



DEPENDENCE OF TAPER ANGLE ON  
ETCHING GAS FLOW RATE

FIG. 21B



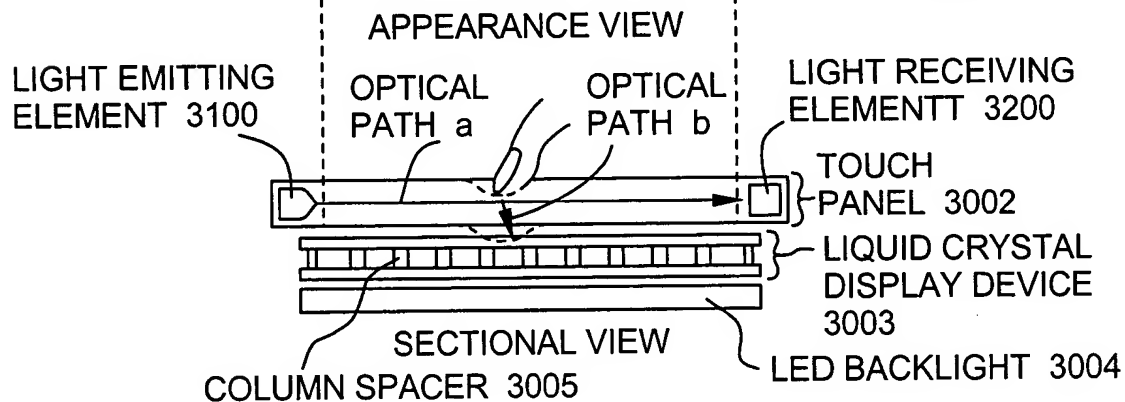
DISPLAY DEVICE 2205  
 TOUCH PANEL 3002  
 LCD PANEL 3003  
 LED BACKLIGHT 3004

IMAGE RECEIVING UNIT 2203

MAIN BODY 2201

CAMERA SECTION 2202

OPERATION SWITCHES 2204



APPEARANCE VIEW AND SECTIONAL VIEW OF PORTABLE INFORMATION TERMINAL (OPTICAL TOUCH PANEL)

FIG. 22A

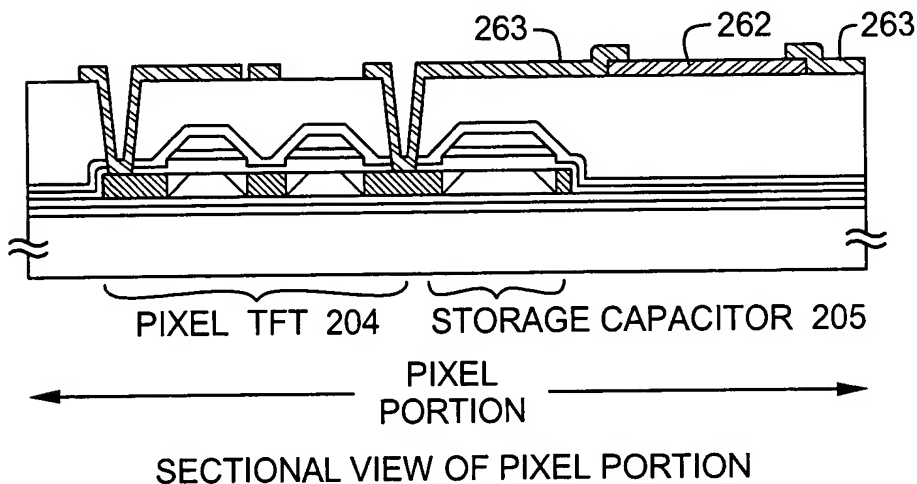
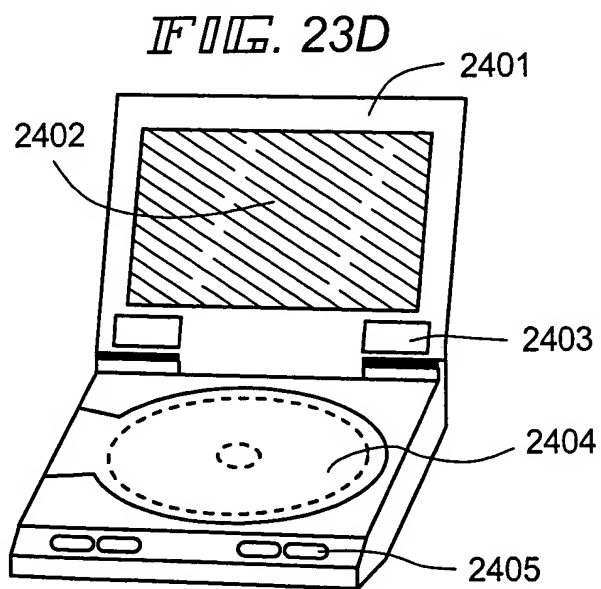
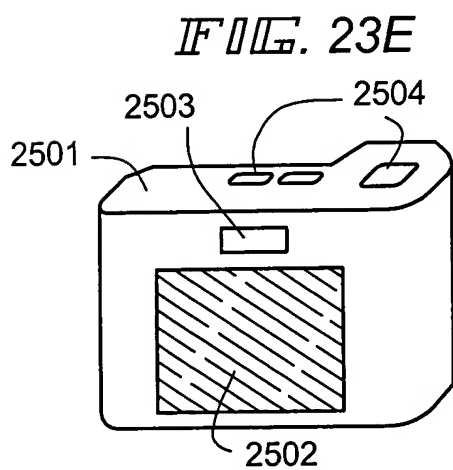
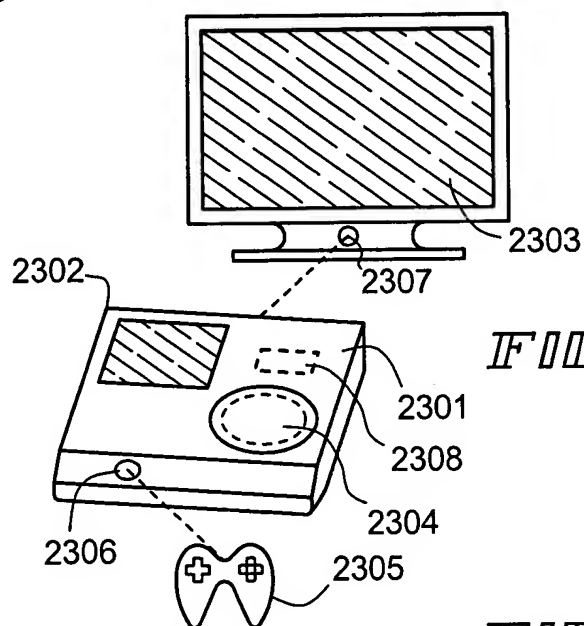
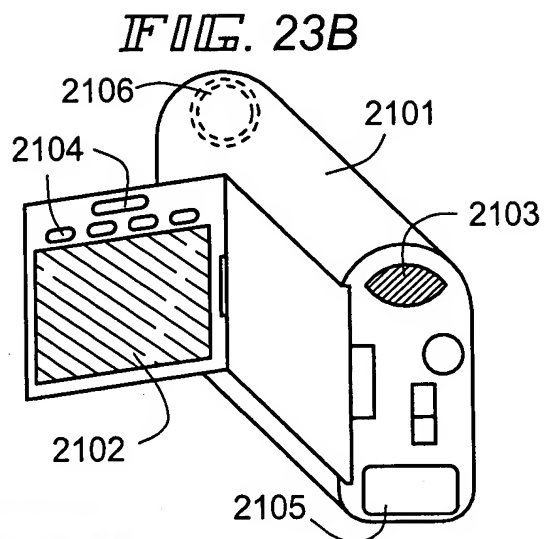
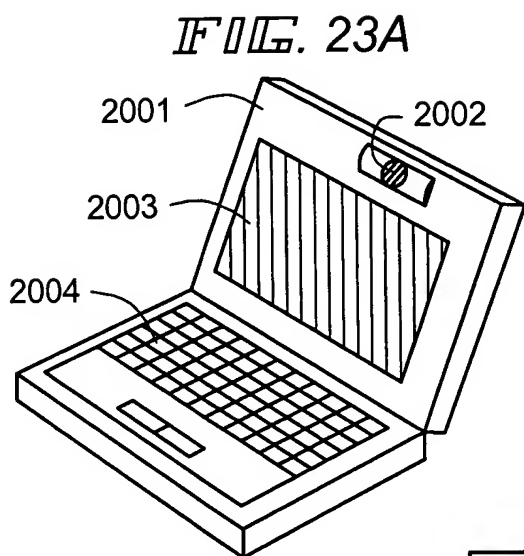


FIG. 22B



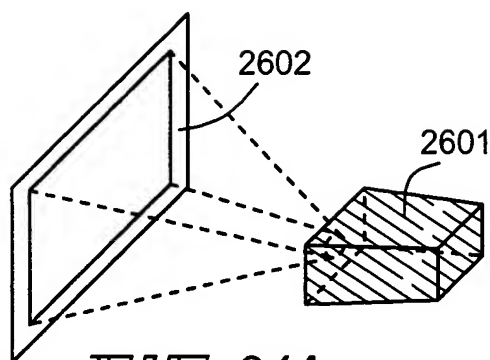


FIG. 24A

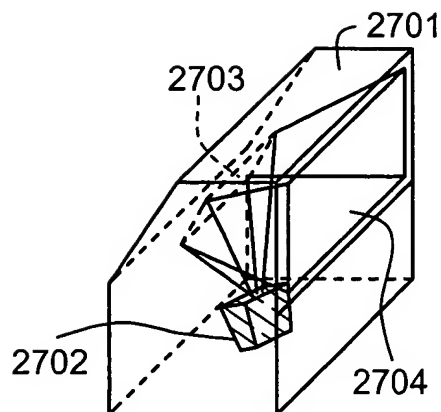
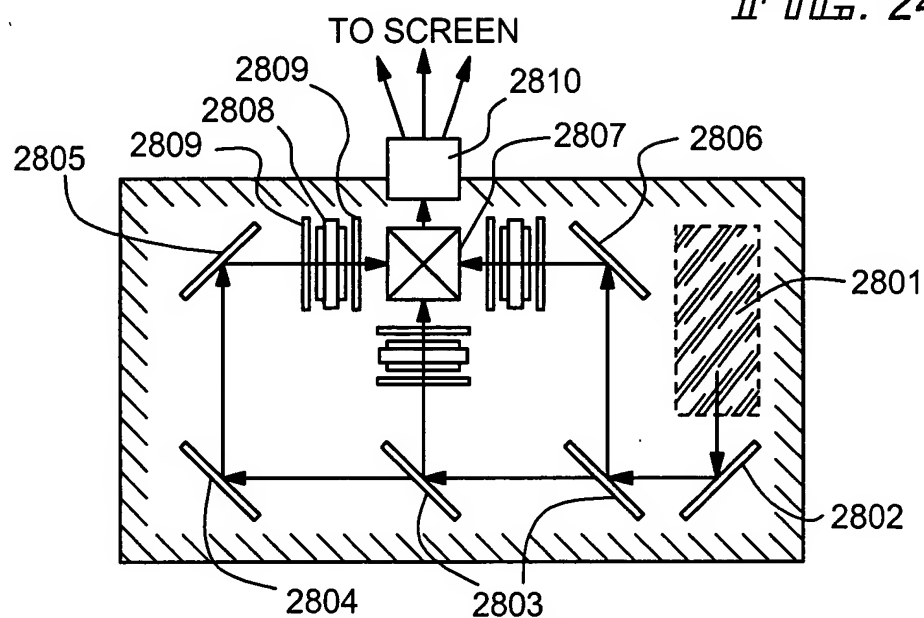


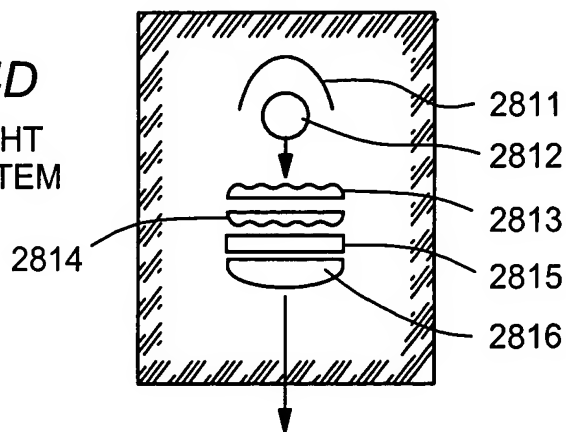
FIG. 24B



OPTICAL LIGHT SOURCE SYSTEM AND  
DISPLAY DEVICES (THREE PLATE TYPE)

FIG. 24C

FIG. 24D  
OPTICAL LIGHT  
SOURCE SYSTEM



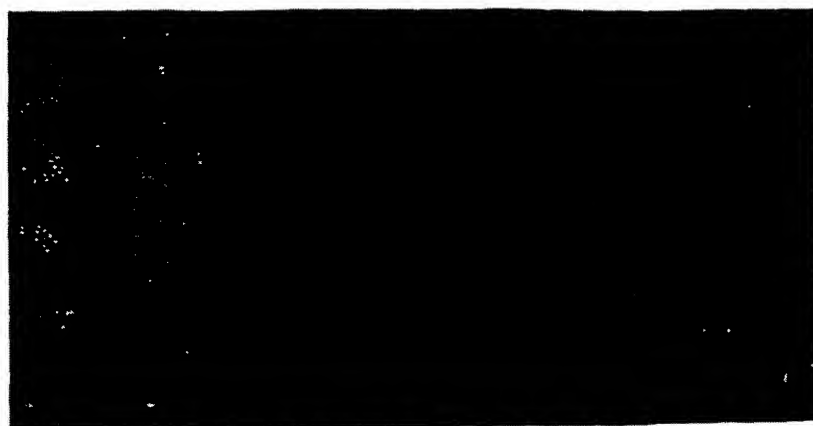


FIG. 25A

X15.0K 2.00μm



FIG. 25B

X15.0K 2.00μm

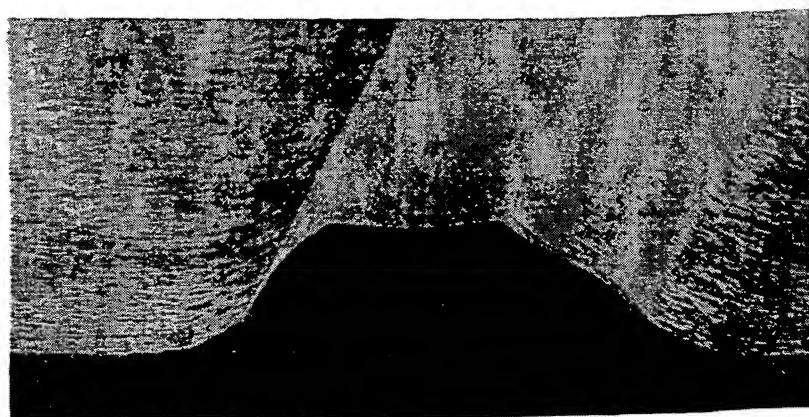


FIG. 25C

X15.0K 2.00μm